

U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified)		Docket No. AMAT/6392/DSM/LO W K/JW	Serial No. 10/010,950
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Applicant Xia, et al.	Confirmation No.: 5694
(Use several sheets if necessary)		Filing Date November 13, 2001	Group 2818



## U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date if Appropriate
<i>De</i>	A1	6,465,366	10/15/2002	Nemani, et al.	438	778	09/12/2000
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	A5	5,638,251	06/10/1997	Goel, et al.	361	313	10/03/1995
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		A12	4,759,947	07/30/1985	Endo, et al.	421		
<i>De</i>		A13	4,532,150					
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*Examiner Initial		Document Number	Date	Country	Class	Subclass	YES	NO
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	B2	00/19498	04/06/2000	WO	H01L	21/027	<input type="checkbox"/>	<input checked="" type="checkbox"/>
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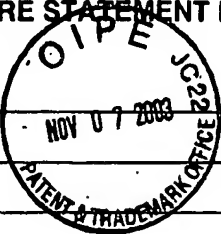
## OTHER ART

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<i>De</i>	C1	U.S. Patent Application No. 09/270,039, filed on March 16, 1999.
	C2	Written Opinion from PCT/US99/22424, dated April 5, 2001.
	C3	PCT Partial International Search Report for US99/22317 dated March 21, 2000.

Examiner

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

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	C5	Dijkstra, et al. "Optimization of Anti-Reflection Layers for Deep UV Lithography", Proceeding of SPIE Optica/Laser Microlithography, Bellingham, SPIE, Volume 1674, (1992) Pages 362-375.
	C6	Omar, M.A. "Elementary Solid State Physics: Principles and Applications," Lowell Technological Institute, Addison-Wesley Publishing Company, 1975, Pages 124 & 125.
	C7	Fukuda, et al. "Highly Reliable SiOF Film Formation by ECR-CVD using SiF <sub>2</sub> H <sub>2</sub> ", (1996) Symposium on VLSI Technology Digest of Technical Papers, IEEE, Pages 114-115.
	C8	PCT International Search Report for US/02/40034, dated May 19, 2003.
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Examiner De		Date Considered Feb-04

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